



Sciences and Innovations in Heat Pump/Refrigeration: Volume II

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Message from the Guest Editors

Dear Colleagues,

This Special Issue is a continuation of the previous Special Issue “Sciences in Heat Pump and Refrigeration”, which was closed in December 2019, and we wish to attract publications related to heat pump and refrigeration. As heat pump and refrigeration are technologies used in a variety of applications (air conditioning, food preservation, hot water and steam generation, drying, cryogenic storage, etc.), the related research area’s span is very broad and includes both basic science and advanced engineering. Therefore, this new Special Issue welcomes basic scientific studies such as the prediction of refrigerant properties by molecular simulation and new materials for thermally driven heat pumps, as well as applied scientific studies that lead to innovation, such as the application of AI and heat transfer enhancement by nanostructures, amongst others.

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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal *Applied Sciences* has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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